Abstracts

Folded U-Shaped Microwire Technology for Ultra-Compact 3D MMICs

K. Onodera, M. Hirano, I. Toyoda, M. Tokumitsu and T. Tokumitsu. "Folded U-Shaped Microwire Technology for Ultra-Compact 3D MMICs." 1996 MTT-S International Microwave Symposium Digest 96.2 (1996 Vol. II [MWSYM]): 1153-1156.

A novel microwire technology has been developed to fabricate 3-dimensional structures for use in ultra-compact GaAs MMICs. By folding metal into a U-shaped wall and burying it in a relatively thick polyimide insulator, vertical microwires can be made with both greatly reduced process complexity and process compatibility with multi-level interconnects. The proposed microwires are suitable for miniature transmission lines, miniature inductors, shielding walls, and multi-function passive elements like baluns and couplers.

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